

December 1994

## 54F/74F32 Quad 2-Input OR Gate

### General Description

This device contains four independent gates, each of which performs the logic OR function.

### Features

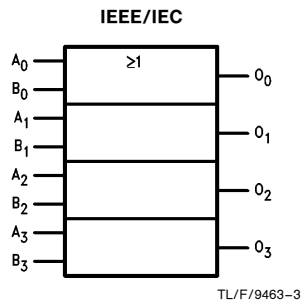
- Guaranteed 4000V minimum ESD protection

| Commercial       | Military         | Package Number | Package Description                               |
|------------------|------------------|----------------|---|
| 74F32PC          |                  | N14A           | 14-Lead (0.300" Wide) Molded Dual-In-Line         |
|                  | 54F32DM (Note 2) | J14A           | 14-Lead Ceramic Dual-In-Line                      |
| 74F32SC (Note 1) |                  | M14A           | 14-Lead (0.150" Wide) Molded Small Outline, JEDEC |
| 74F32SJ (Note 1) |                  | M14D           | 14-Lead (0.300" Wide) Molded Small Outline, EIAJ  |
|                  | 54F32FM (Note 2) | W14B           | 14-Lead Cerpack                                   |
|                  | 54F32LM (Note 2) | E20A           | 20-Lead Ceramic Leadless Chip Carrier, Type C     |

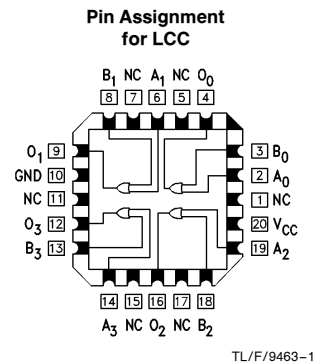
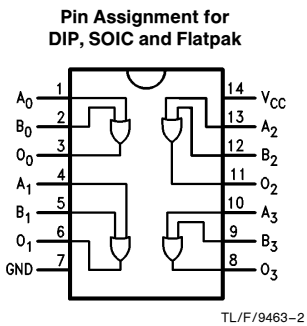
**Note 1:** Devices also available in 13" reel. Use suffix = SCX and SJX.

**Note 2:** Military grade device with environmental and burn-in processing. Use suffix = DMOB, FMOB and LMOB.

### Logic Symbol



### Connection Diagrams



### Unit Loading/Fan Out

| Pin Names  | Description | 54F/74F          |   |
|------------|-------------|------------------|---|
|            |             | U.L.<br>HIGH/LOW | Input $I_{IH}/I_{IL}$<br>Output $I_{OH}/I_{OL}$ |
| $A_n, B_n$ | Inputs      | 1.0/1.0          | $20 \mu A / -0.6 \text{ mA}$                    |
| $O_n$      | Outputs     | 50/33.3          | $-1 \text{ mA} / 20 \text{ mA}$                 |

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## Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

|                                 |                 |
|---------------------------------|-----------------|
| Storage Temperature             | –65°C to +150°C |
| Ambient Temperature under Bias  | –55°C to +125°C |
| Junction Temperature under Bias | –55°C to +175°C |
| Plastic                         | –55°C to +150°C |

V<sub>CC</sub> Pin Potential to Ground Pin –0.5V to +7.0V

Input Voltage (Note 2) –0.5V to +7.0V

Input Current (Note 2) –30 mA to +5.0 mA

Voltage Applied to Output in HIGH State (with V<sub>CC</sub> = 0V)

|                   |                          |
|-------------------|--------------------------|
| Standard Output   | –0.5V to V <sub>CC</sub> |
| TRI-STATE® Output | –0.5V to +5.5V           |

Current Applied to Output in LOW State (Max) twice the rated I<sub>OL</sub> (mA)

ESD Last Passing Voltage (Min) 4000V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

## Recommended Operating Conditions

|                              |                 |
|------------------------------|-----------------|
| Free Air Ambient Temperature |                 |
| Military                     | –55°C to +125°C |
| Commercial                   | 0°C to +70°C    |
| Supply Voltage               |                 |
| Military                     | +4.5V to +5.5V  |
| Commercial                   | +4.5V to +5.5V  |

## DC Electrical Characteristics

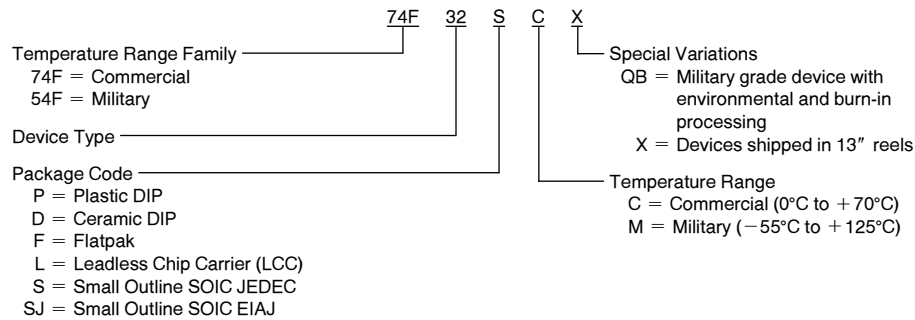
| Symbol           | Parameter                         | 54F/74F  |                   |      | Units | V <sub>CC</sub> | Conditions  |
|------------------|-----------------------------------|--|-------------------|------|-------|-----------------|---|
|                  |                                   | Min  | Typ               | Max  |       |                 |   |
| V <sub>IH</sub>  | Input HIGH Voltage                | 2.0  |                   |      | V     |                 | Recognized as a HIGH Signal   |
| V <sub>IL</sub>  | Input LOW Voltage                 | 0.8  |                   |      | V     |                 | Recognized as a LOW Signal  |
| V <sub>CD</sub>  | Input Clamp Diode Voltage         | –1.2   |                   |      | V     | Min             | I <sub>IN</sub> = –18 mA  |
| V <sub>OH</sub>  | Output HIGH Voltage               | 54F 10% V <sub>CC</sub><br>74F 10% V <sub>CC</sub><br>74F 5% V <sub>CC</sub> | 2.5<br>2.5<br>2.7 |      | V     | Min             | I <sub>OH</sub> = –1 mA<br>I <sub>OH</sub> = –1 mA<br>I <sub>OH</sub> = –1 mA |
| V <sub>OL</sub>  | Output LOW Voltage                | 54F 10% V <sub>CC</sub><br>74F 10% V <sub>CC</sub>                           | 0.5<br>0.5        |      | V     | Min             | I <sub>OL</sub> = 20 mA<br>I <sub>OL</sub> = 20 mA                            |
| I <sub>IH</sub>  | Input HIGH Current                | 54F<br>74F   | 20.0<br>5.0       |      | μA    | Max             | V <sub>IN</sub> = 2.7V  |
| I <sub>BVI</sub> | Input HIGH Current Breakdown Test | 54F<br>74F   | 100<br>7.0        |      | μA    | Max             | V <sub>IN</sub> = 7.0V  |
| I <sub>CEX</sub> | Output HIGH Leakage Current       | 54F<br>74F   | 250<br>50         |      | μA    | Max             | V <sub>OUT</sub> = V <sub>CC</sub>  |
| V <sub>ID</sub>  | Input Leakage Test                | 74F  | 4.75              |      | V     | 0.0             | I <sub>ID</sub> = 1.9 μA<br>All Other Pins Grounded                           |
| I <sub>OD</sub>  | Output Leakage Circuit Current    | 74F  | 3.75              |      | μA    | 0.0             | V <sub>IOD</sub> = 150 mV<br>All Other Pins Grounded                          |
| I <sub>IL</sub>  | Input LOW Current                 |  | –0.6              |      | mA    | Max             | V <sub>IN</sub> = 0.5V  |
| I <sub>OS</sub>  | Output Short-Circuit Current      |  | –60               | –150 | mA    | Max             | V <sub>OUT</sub> = 0V   |
| I <sub>CCH</sub> | Power Supply Current              |  | 6.1               | 9.2  | mA    | Max             | V <sub>O</sub> = HIGH   |
| I <sub>CCL</sub> | Power Supply Current              |  | 10.3              | 15.5 | mA    | Max             | V <sub>O</sub> = LOW  |

## AC Electrical Characteristics

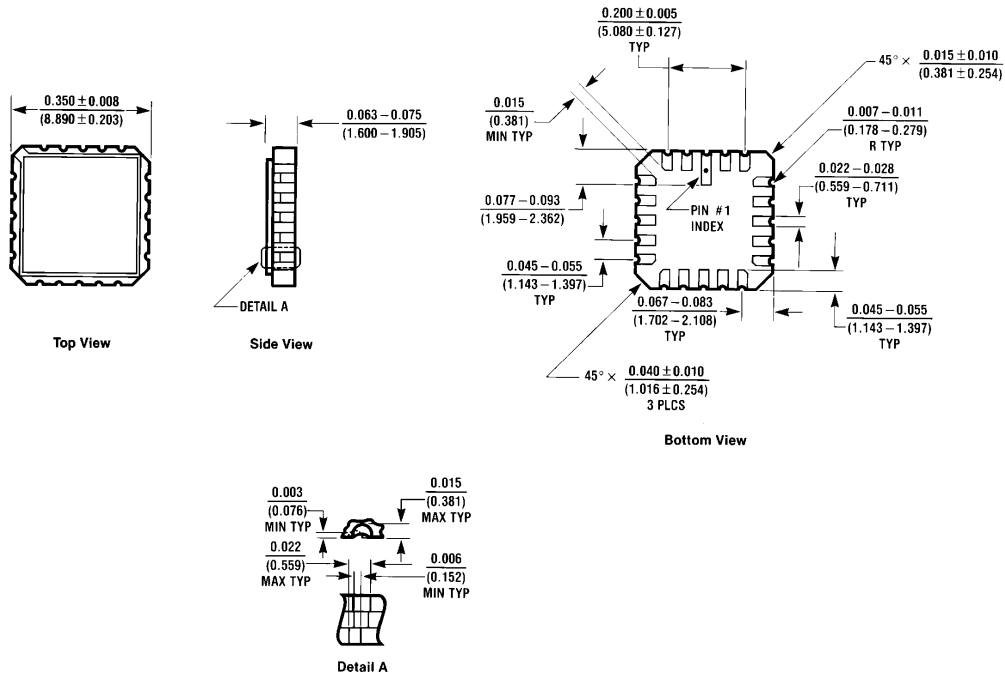
| Symbol           | Parameter   | 74F   |     |     | 54F  |     | 74F  |     | Units |
|------------------|---|---|-----|-----|--|-----|--|-----|-------|
|                  |   | T <sub>A</sub> = +25°C<br>V <sub>CC</sub> = +5.0V<br>C <sub>L</sub> = 50 pF |     |     | T <sub>A</sub> , V <sub>CC</sub> = Mil<br>C <sub>L</sub> = 50 pF |     | T <sub>A</sub> , V <sub>CC</sub> = Com<br>C <sub>L</sub> = 50 pF |     |       |
|                  |   | Min   | Typ | Max | Min  | Max | Min  | Max |       |
| t <sub>PLH</sub> | Propagation Delay                                 | 3.0   | 4.2 | 5.6 | 3.0  | 7.5 | 3.0  | 6.6 | ns    |
| t <sub>PHL</sub> | A <sub>n</sub> , B <sub>n</sub> to O <sub>n</sub> | 3.0   | 4.0 | 5.3 | 2.5  | 7.5 | 3.0  | 6.3 |       |

## Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



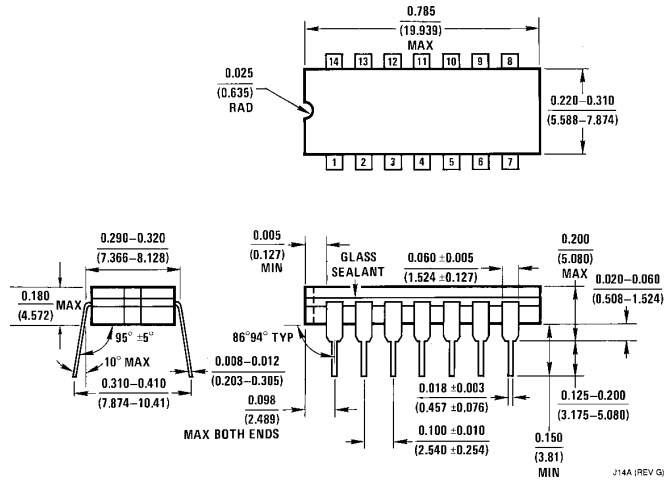
## Physical Dimensions inches (millimeters)



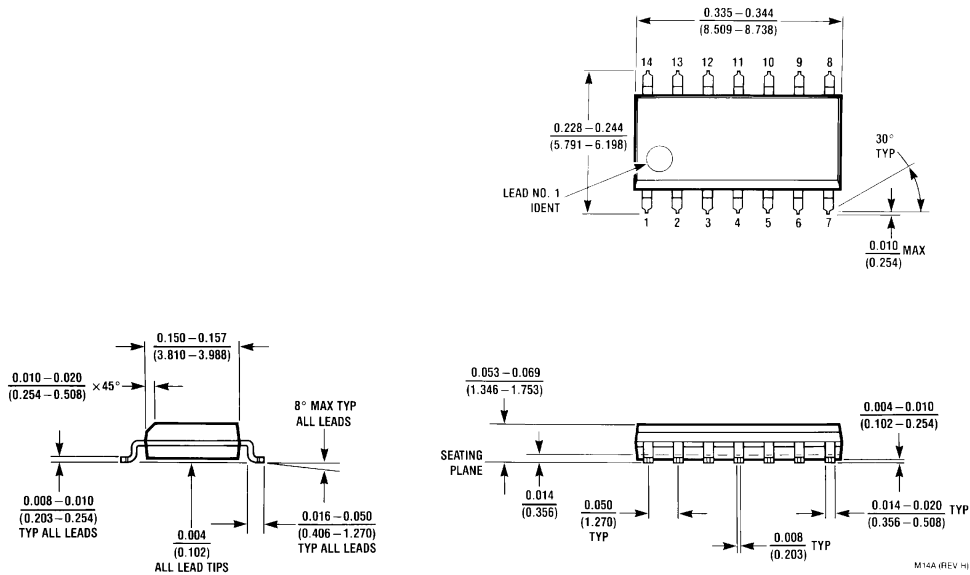
20-Lead Ceramic Leadless Chip Carrier (L)  
 NS Package Number E20A

E20A (REV D)

**Physical Dimensions** inches (millimeters) (Continued)

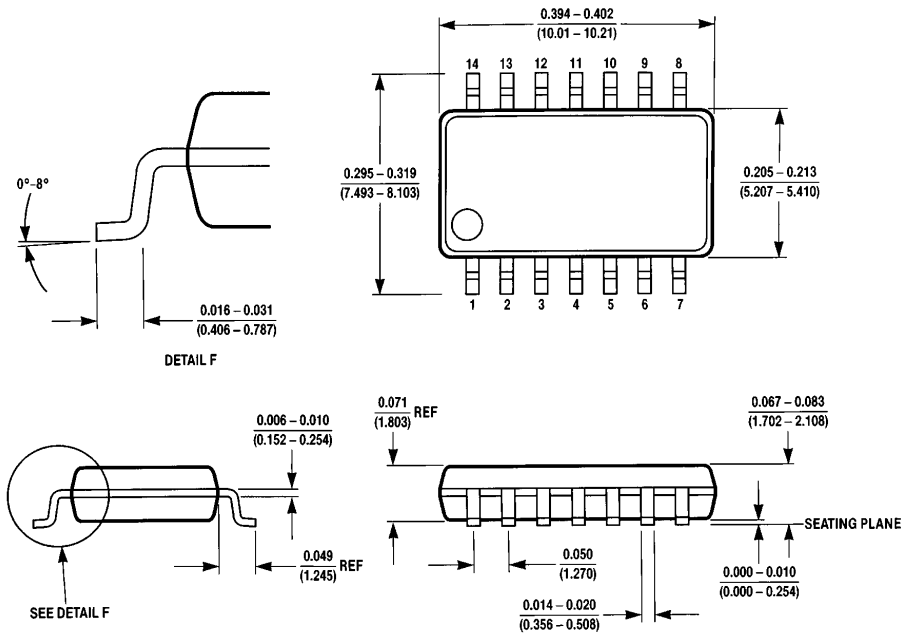


**14-Lead Ceramic Dual-In-Line Package (D)**  
NS Package Number J14A



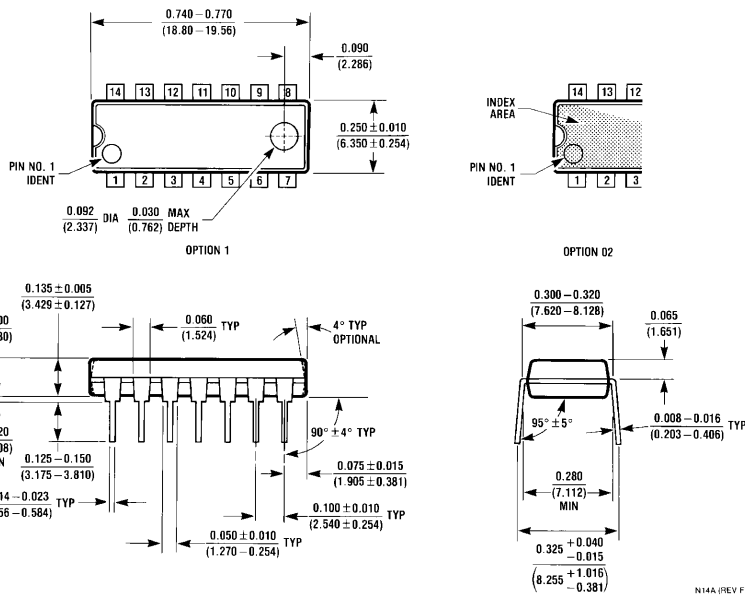
**14-Lead (0.150" Wide) Molded Small Outline Package, JEDEC (S)**  
NS Package Number M14A

**Physical Dimensions** inches (millimeters) (Continued)



M14D (REV A)

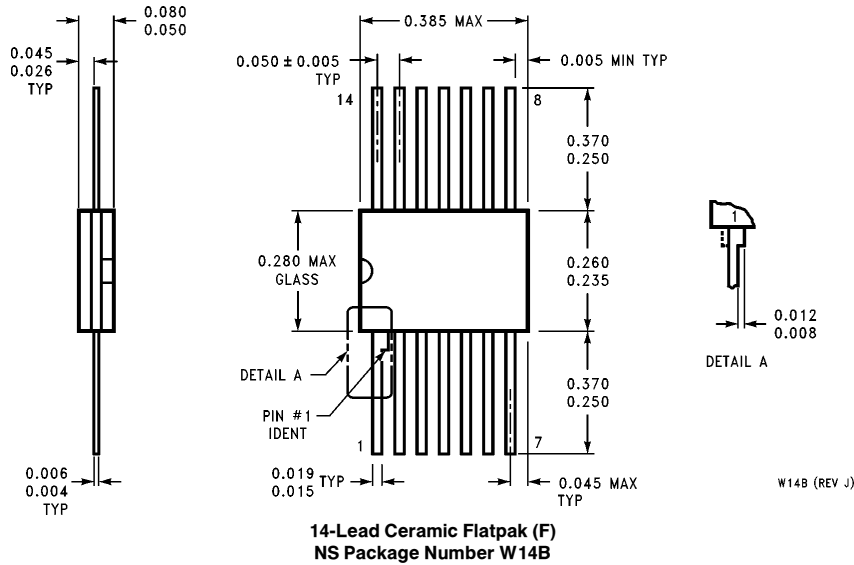
**14-Lead (0.300" Wide) Molded Small Outline Package, EIAJ (SJ)  
NS Package Number M14D**



N14A (REV F)

**14-Lead (0.300" Wide) Molded Dual-In-Line Package (P)  
NS Package Number N14A**

**Physical Dimensions** inches (millimeters) (Continued)



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